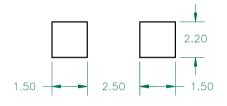
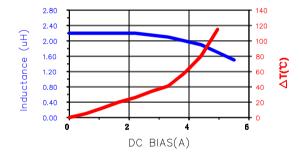
## MGV04022R2M-10

## PHYSICAL DIMENSIONS:

Α	4.50	$\pm$	0.50
В	4.10	$\pm$	0.30
С	2.00	±	0.30
D	1.50	±	0.30
Ε	1.00	±	0.50

## LAND PATTERNS FOR REFLOW SOLDERING

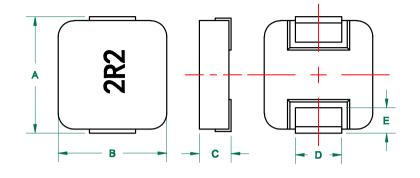




## ELECTRICAL SPECIFICATION @ 25°C

	Min	Nom	Max	
INDUCTANCE (uH) L @ 100 KHz/0.25V ± 20%	1.76	2.20	2.64	
DCR <b>(Ω)</b>			0.058	

Saturation Current <sup>3</sup> Isat (A)	5.00
Temperature Rise Current Irms <sup>4</sup> (A)	3.00









NOTES: UNLESS OTHERWISE SPECIFIED

- 1.COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2.OPERATION TEMPERATURE RANGE:
  - -40°C~+125°C (INCLUDING SELF-HEATING).
- 3.SATURATION CURRENT Isat IS DEFINED AS MAXIMUM AMOUNT OF CURRENT BY WHICH INDUCTANCE WILL DROP BY TYPICAL VALUE OF 30% OF INITIAL INDUCTANCE (Ta=25±5°C).
- 4.TEMPERATURE RISE CURRENT (Irms): DC CURRENT THAT CAUSES THE TEMPERATURE RISE (  $\Delta T \leq 40^{\circ}$ C) FROM 25°C AMBIENT.

DIMENSIONS ARE IN mm.			This print is the property of Lair Tech, and is loaned in confidence	ď				
				subject to return upon request		<b>.</b> _		
				with the understanding that no		La	iro	1
				copies shall be made without th written consent of Laird Tech. A	e	TECHN	OLOGI	
				rights to design or invention are				
				reserved.				
				PROJECT/PART NUMBER:	REV	PART	TYPE:	DRAWN BY:
С	CHANGE DIMENSIONS AND ADD CURVE	01/04/13	Q.O	MGV04022R2M-10	)   (		OWER UCTOR	QIU
В	CORRECT MARKING AND DIMENSION	03/21/12	QIU	DATE: 01/16/12	SCALE:	NTS	SHEET:	
Α	ORIGINAL DRAFT	01/16/12	QIU		TOOL #		4 .	
REV	DESCRIPTION	DATE	INT	MGV04022R2M-10-C	1001.	-	1	of 1